

## CLAIMS

1. A silicon containing curing composition comprising at least one silicon containing polymer selected from the following components (A), (B), and (C) and the following component (D) as a catalyst, provided that the composition contains  
5 both the components (A) and (B) when the component (C) is absent:

(A) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of  $\text{Si-R}^1$ ,  $\text{Si-O-R}^2$ , and  $\text{Si-R}^3\text{-OCOC(R}^4\text{)=CH}_2$ , wherein  $\text{R}^1$  and  $\text{R}^2$  each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group;  $\text{R}^3$  represents an  
10 alkylene group having 1 to 9 carbon atoms and/or an arylene group; and  $\text{R}^4$  represents hydrogen or a methyl group,

having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

15 (B) A silicon containing polymer having an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

(C) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of  $\text{Si-R}^1$ ,  $\text{Si-O-R}^2$ , and  $\text{Si-R}^3\text{-OCOC(R}^4\text{)=CH}_2$ ,  
20 wherein  $\text{R}^1$  and  $\text{R}^2$  each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group;  $\text{R}^3$  represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group; and  $\text{R}^4$  represents hydrogen or a methyl group,

and an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and  
25 containing 20% by weight or less of a component whose weight average molecular

weight is 1000 or less.

(D) A platinum-based catalyst as a catalyst for curing reaction.

2. The silicon containing curing composition according to claim 1, wherein the total aryl group and arylene group content of the total silicon containing polymers as
- 5 components (A), (B), and (C) is 0.1% to 50% by weight.
3. The silicon containing curing composition according to claim 1 or 2, which further comprises a metal oxide fine powder as component (E).
4. A cured product obtained by heat curing the silicon containing curing composition according to any one of claims 1 to 3.